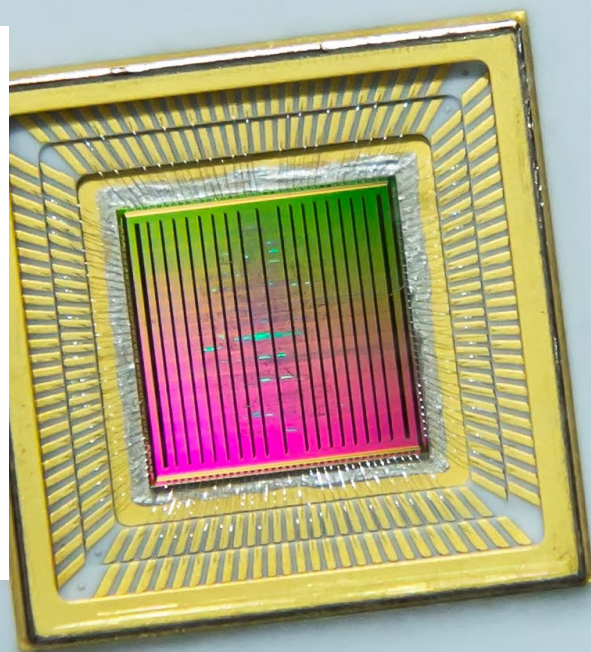


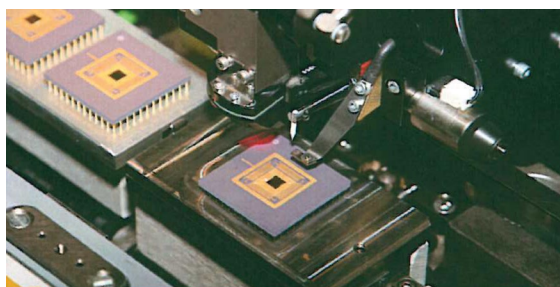
Ceramic Packaging and Assembly

QP Technologies' Ceramic Packages and Assembly enable faster design verification and quicker time to market for your new devices. When ceramic packages are the right vehicle for your prototype devices, QP Technologies can provide a full turnkey solution. We will either use your packages or procure the packages from industry-leading ceramic suppliers and assemble your devices to your specifications.



Advantages:

- High temperature, high reliability capability
- Wide range of package and lid configurations
- Turnaround in 24 hours or less
- ITAR Registered
- ISO 9001:2015 Certified
- ISO 13485:2016 Certified



Assembly Options Include:

- Die attach: filled epoxies, silver-glass, silver-filled cyanate ester and gold eutectic
- Nondestructive bond pull for Class S standard
- Solder, glass or epoxy lid seal
- Glop-top available
- Marking: MIL standard permanency

Flexibility

QP Technologies can procure and assemble virtually every type of ceramic package available, all in the most common sizes and configurations and open-tooled designs. No matter how large or small the requirement, we offer a reliable way to shorten leadtimes and reduce cost of materials. Packages are available with a variety of lids including taped-on, ceramic, combo, glass and hermetically sealed.

Speed

When you need a full turnkey solution, QP Technologies can do it all – from wafer dicing and backgrinding, package procurement and preparation to die attach, wire bonding, encapsulation, remolding and marking. We deliver production-quality prototype parts for internal testing or customer samples to meet your deadline.